

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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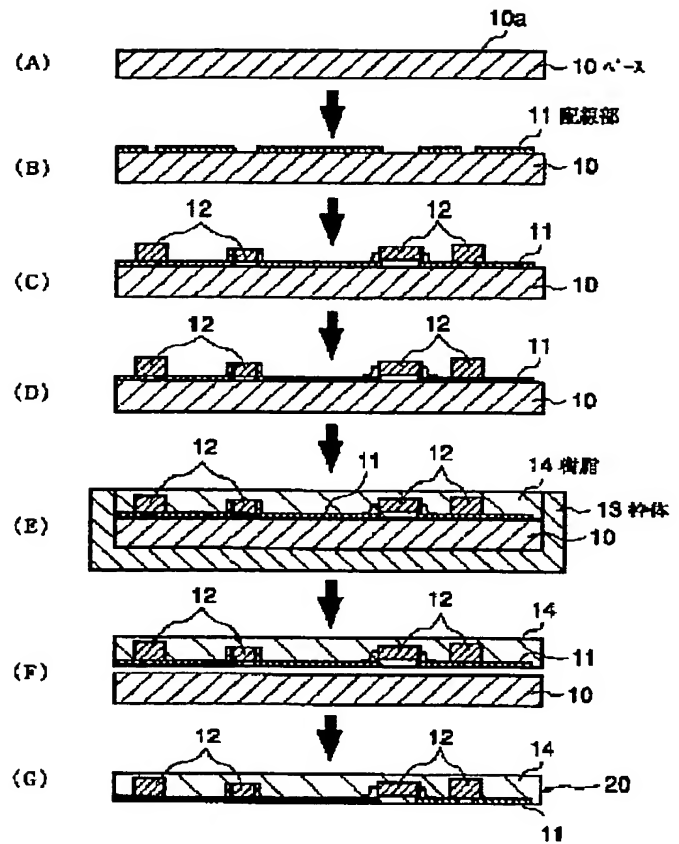
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TITLE : MANUFACTURE OF CIRCUIT BOARD



**ABSTRACT :** PROBLEM TO BE SOLVED: To efficiently manufacture a thinned circuit board by a method wherein electronic components are arranged on wiring parts, the components and the wiring parts are sealed with a resin and the wiring parts are separated from a base along with the components to complete the circuit board.

**SOLUTION:** Wiring parts 11 are formed on a base 10 in a prescribed pattern, electronic components 12, such as a resistor and a capacitor, are mounted on the wiring parts 11 and the wiring parts 11 are cured by heating to fix the components 12 on the wiring parts 11. Then the base 10, the wiring parts 11 and the components 12 are housed in a frame body 13, a resin 14 is filled in the frame body 13 to cure the resin 14 and the wiring parts 11 and the components 12 are sealed with the resin 14. After that, the wiring parts 11 and the resin 14 are separated from the base 10 along with the components 12 to complete a circuit board 20. Thereby, the members for arranging and fixing the components 12 become unnecessary separately from the wiring pattern, and the whole circuit board 20 can be thinned.

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